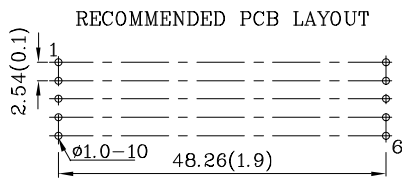
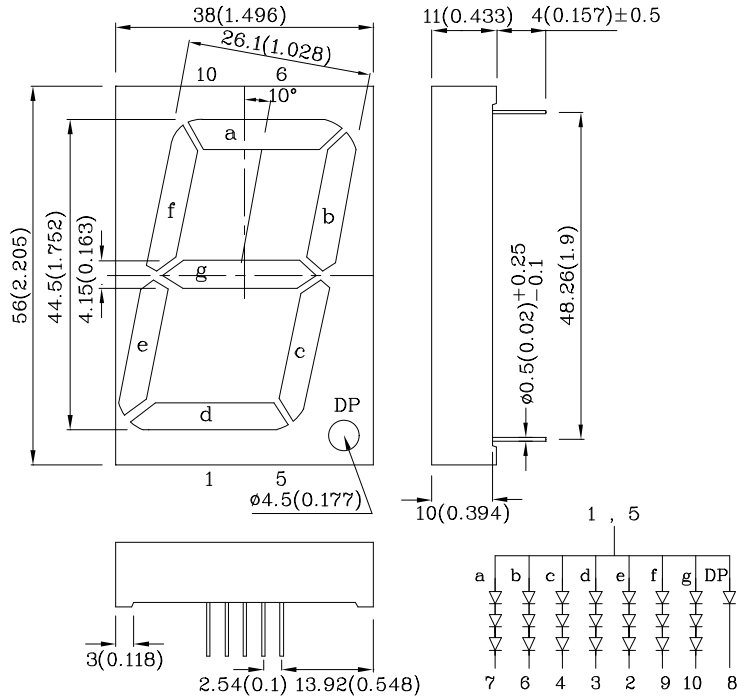


Features

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



Package Schematics



Notes:

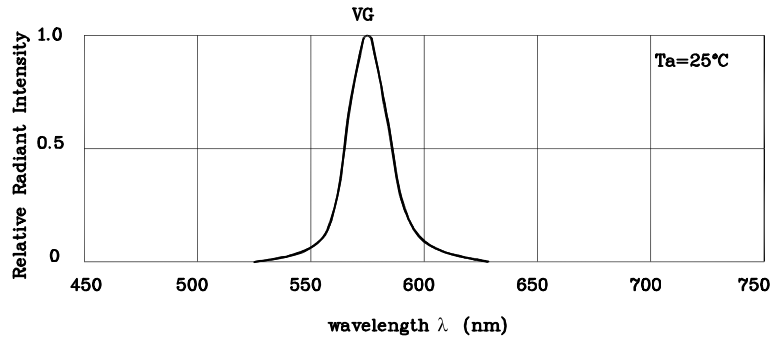
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		VG (AlGaInP)	Unit
Reverse Voltage (Per Chip)	V _R	5	V
Forward Current (D _p)	I _F	30 (30)	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width (D _p)	i _{FS}	150 (150)	mA
Power Dissipation (Per Chip)	P _D	75	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds		

Operating Characteristics (T _A =25°C)		VG (AlGaInP)	Unit
Forward Voltage (Typ.) (D _p) (I _F =10mA)	V _F	6 (2)	V
Forward Voltage (Max.) (D _p) (I _F =10mA)	V _F	7.5 (2.5)	V
Reverse Current (Max.) (Per Chip) (V _R =5V)	I _R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _P	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λ _D	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	15	pF

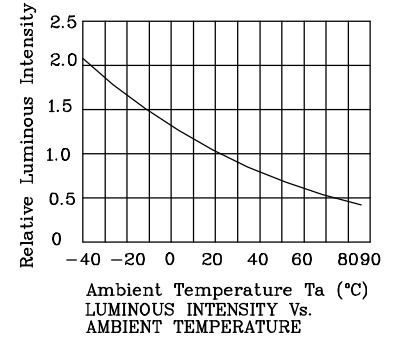
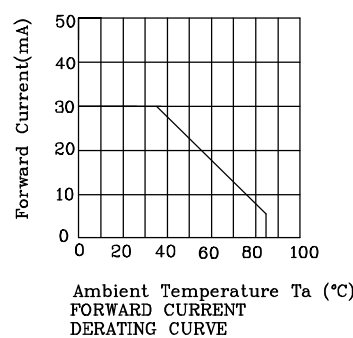
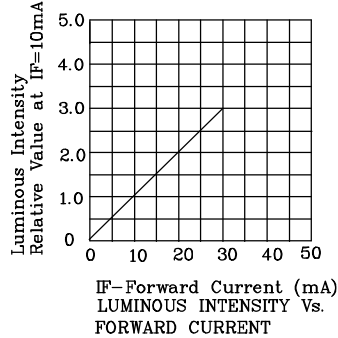
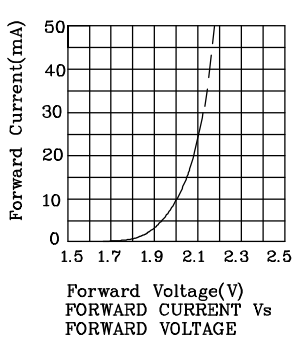
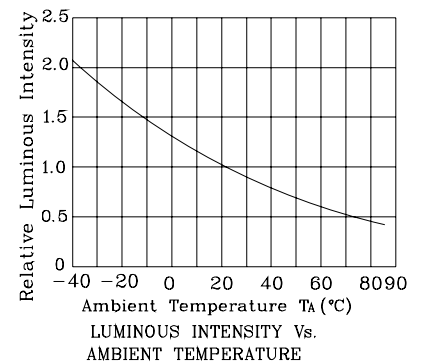
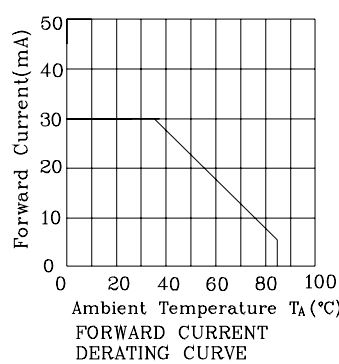
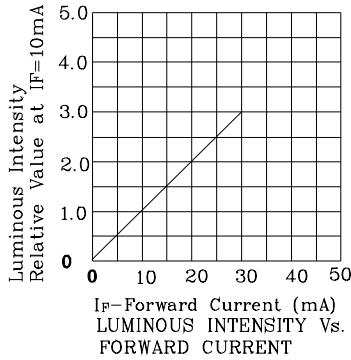
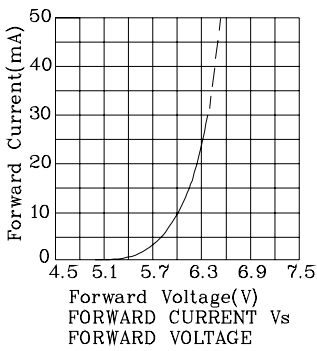
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127-2007* nm λ _P	Description
			min.	typ.		
XDVG46A	Green	AlGaInP	52000	139990	574*	Common Anode , Rt.Hand Decimal.
			21000*	49990*		

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

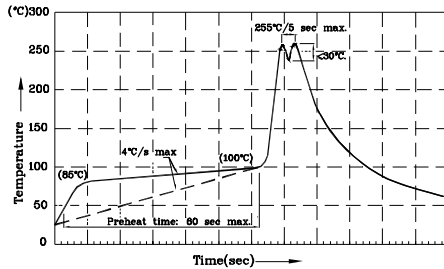


RELATIVE INTENSITY Vs. CIE WAVELENGTH

❖ VG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- Notes:
1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
 3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
 4. Fixtures should not incur stress on the component when mounting and during soldering process.
 5. SAC 305 solder alloy is recommended.
 6. No more than one wave soldering pass.

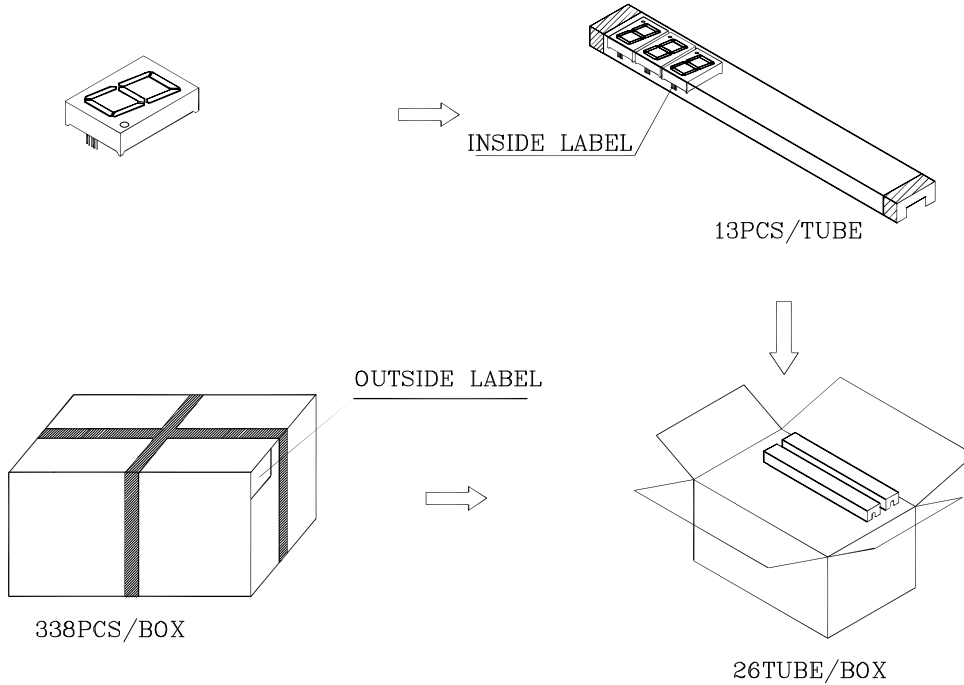
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

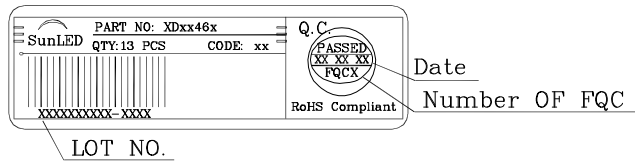
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

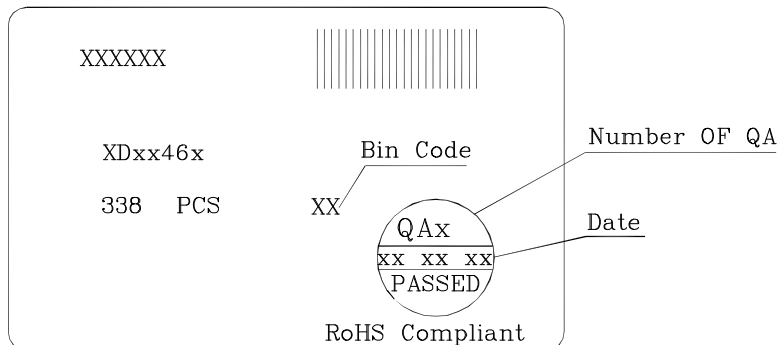
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



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